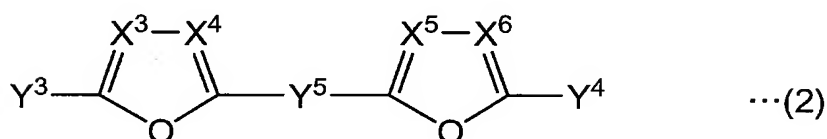
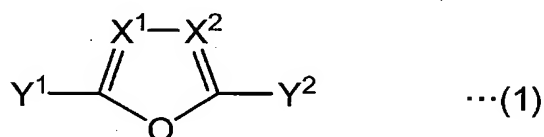


CLAIMS

1. A photosensitive resin composition comprising (A) a binder polymer, (B) a photopolymerizing compound with an ethylenic unsaturated bond, (C) a photopolymerization initiator and (D) a compound represented by the following general formula (1) or (2).

[Chemical Formula 1]



[wherein X¹, X², X³, X⁴, X⁵ and X⁶ each independently represent a CH group, CCH₃ group, CC₂H₅ group or nitrogen, Y¹, Y², Y³ and Y⁴ each independently represent optionally substituted aryl, and Y⁵ represents optionally substituted arylene].

2. A photosensitive resin composition according to claim 1, wherein component (C) contains a 2,4,5-triarylimidazole dimer.

3. A photosensitive resin composition according to claim 1 or 2, wherein component (B) contains a bisphenol A-type (meth)acrylate compound.

4. A photosensitive resin composition according to any one of claims 1 to 3, wherein the acid value of component (A) is 30-200 mgKOH/g and the weight-average molecular weight is 20,000-300,000.

5. A photosensitive resin composition according to any one of claims 1 to 4, wherein the component (A) content is 20-90 parts by weight, the component (B) content is 10-80 parts by weight, the component (C) content is 0.01-20 parts by weight and the component (D) content is 0.001-20 parts by weight, with respect to 100 parts by weight as the total of component (A) and component (B).

6. A photosensitive element comprising a support and a photosensitive resin composition layer composed of a photosensitive resin composition according to any one of claims 1 to 5 formed on the support.

7. A resist pattern forming method which comprises laminating a photosensitive resin composition layer for a photosensitive element according to claim 6 on a circuit forming board, irradiating prescribed sections of the photosensitive resin composition layer with active light rays for photocuring of the exposed sections, and then removing the non-exposed sections.

8. A process for manufacturing a printed circuit board which comprises etching or plating a circuit forming board having a resist pattern formed thereon by a resist pattern forming method according to claim 7.